

Bill of Materials

TI DESIGNS

Ref.	Part name	Pcs/unit	Description	Manufacturer	Part number	Supplier	
C5-6	C_0603	2	Capacitor, general, 0603; Do not mount				
C3;C7	C_100N_0603_X7R_K_50	2	Capacitor, 100n, 0603, X7R, 10%, 50V	Murata	GRM188R71H104KA93D		
C1-2;C4	C_10U_0603_X5R_M_6P3	3	Capacitor, 10u, 0603, X5R, 20%, 6.3V	Murata	GRM188R60J106ME47D		
L1	LPS3015-222ML	1	Power inductor, shielded, 20% tol, SMT, RoHS	Coilcraft	LPS3015-222ML	ACTE	
O1	OSC32K_ASVK	1					
P1-2;P10-11;P20-21	PINROW_1X10_NEW	6	Do not mount				
P3	PINROW_1X3_REDUCED	1	Do not mount				
P4	PINROW_2X2	1	Do not mount				
R5-6;R8-9;R14-15	R_0603	6	Resistor, general, 0603; Do not mount				
R2-4;R7;R10;R12-13;R16-20;R23;R25-26	R_0_0603	15	Resistor, 0 ohm, 0603, ±1%	Koa	RK73Z1JTDD	ELFA	
R22	R_180K_0603_G	1	Resistor, 180k ohms, 0603, ±2%	Koa	RK73H1JTDD1803F	ELFA	
R21	R_1M0_0603_J	1	Resistor, 1m0 ohm, 0603, 5%	Koa	RK73H1JTDD1004F (±1%)	ELFA	
RF1-2	SMD_HEADER_2X10	2	SMD pinrow header, .050 spacing, 2x10	Samtec	TFM-110-02-SM-D-A-K-TR	Abacus	
LP1;LP2	SOCKET_1X10	2	1x10 pinrow, 2.54mm pitch, through-hole	Samtec	SSQ-110-23-L-S	Samtec	
LP1X;LP2X	SOCKET_1X10	2	2x10 socket, 2.54mm pitch, through-hole	Samtec	SSQ-110-23-L-D	Samtec	
U1	TPS63030	1	Do not mount				
P5	USB-B_MICRO	1	Micro USB receptacle, standard type B, SMD	Tyco	1981568-1	Digikey	
D1	BAT54J	1	Diode, Si, Schottkey	NXP	BAT54J	Digikey	
	SUM	49					

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